

φ0.090ドリル加工事例

φ0.090 Ultra Micro-Hole Drilling Performance

用途 半導体パッケージ、各種デバイス用基板等 FBGA、BGA、Device substrate etc...

加工条件 [Drilling Condition]

Work Material : MCL-E-679FG(R) t0.1(Double Sided) x **5 stacks** (4/4 μmCopper)

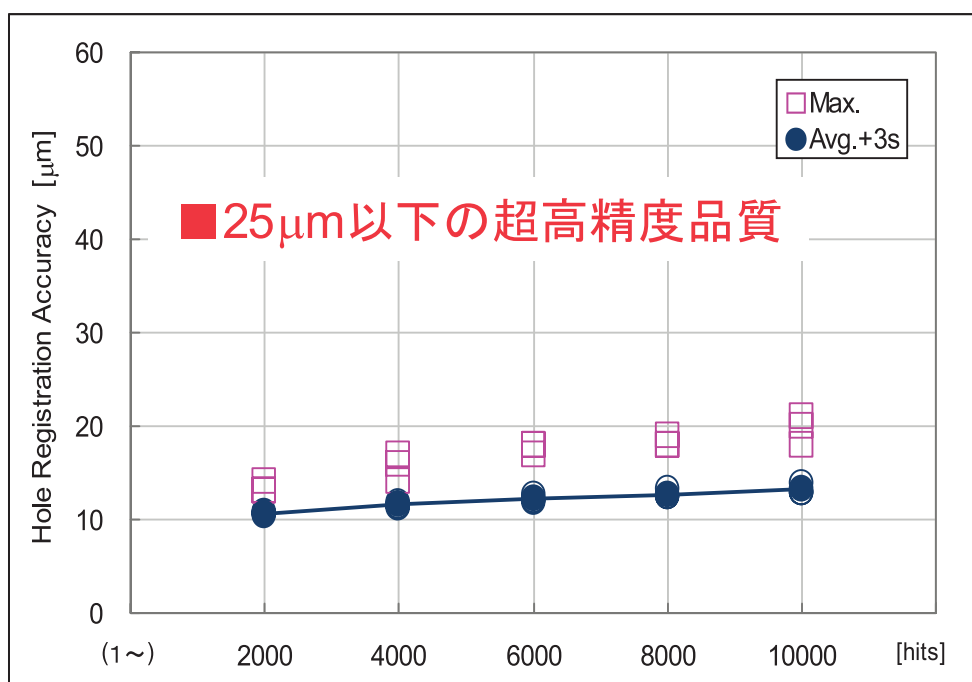
S : 350,000 min⁻¹ F : 1.75 m/min f : 5 μm/rev

Set Life : 10,000 hits

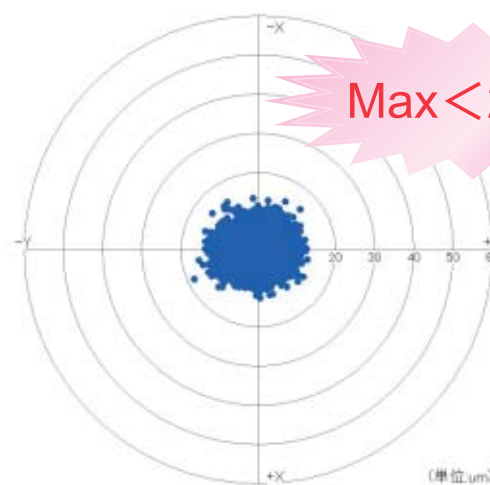
New E/B LE900使用
Under Development



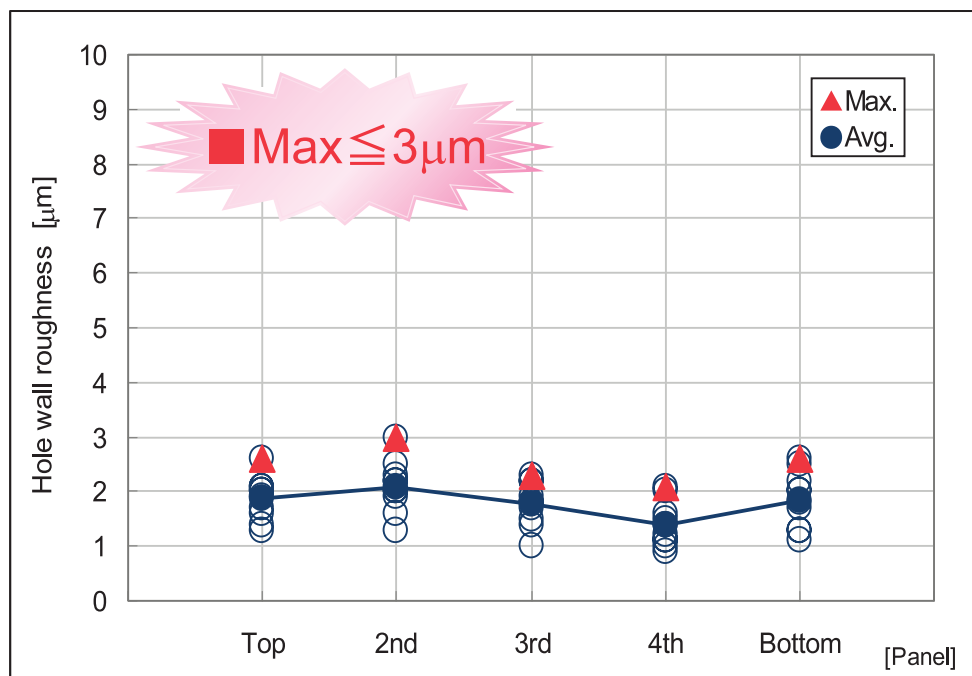
穴位置精度 [Hole Registration Accuracy]



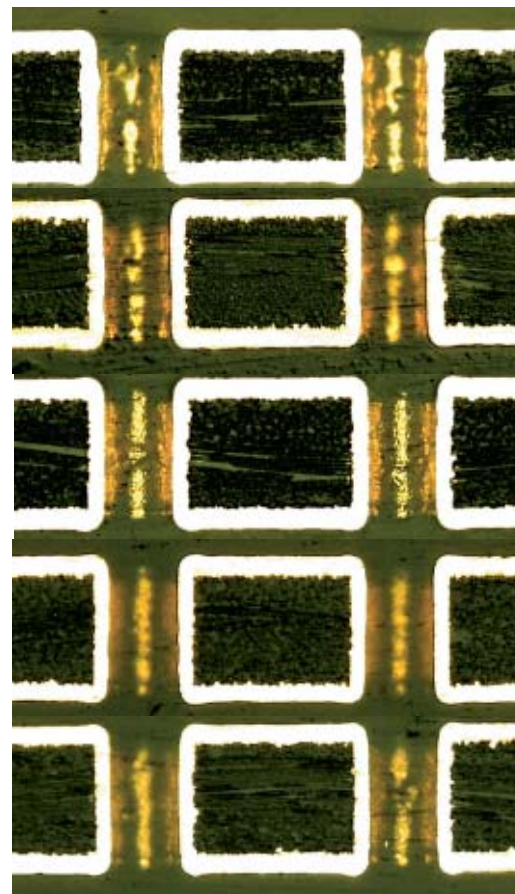
10,000 hits



内壁粗さ [Hole Wall Quality at 10,000 hits]



Top



2nd

3rd

4th

Bottom